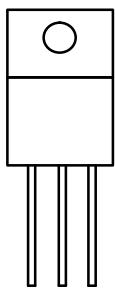


N-Channel Enhancement-Mode Transistor

Product Summary

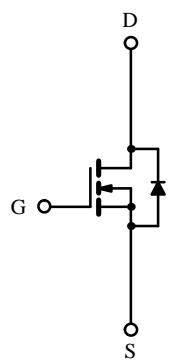
V_{(BR)DSS} (V)	r_{D(on)} (Ω)	I_D (A)
100	0.075	20

TO-257AB
Hermetic Package



Case Isolated

Top View



N-Channel MOSFET

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	± 20	
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	I _D	20	A
		12	
Pulsed Drain Current	I _{DM}	80	
Maximum Power Dissipation	P _D	60	W
		20	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C
Lead Temperature (1/16" from case for 10 sec.)	T _L	300	

Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	R _{thJA}		80	°C/W
Maximum Junction-to-Case	R _{thJC}		2.1	
Case-to-Sink	R _{thCS}	1.0		

Subsequent updates to this data sheet may be obtained via facsimile by calling Siliconix FaxBack, 1-408-970-5600. Please request FaxBack document #1460.

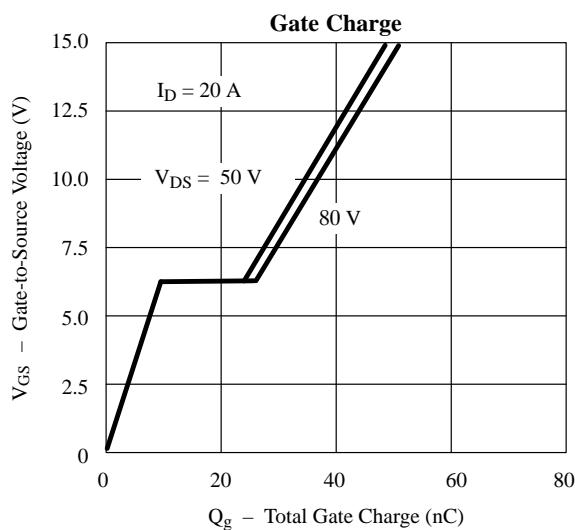
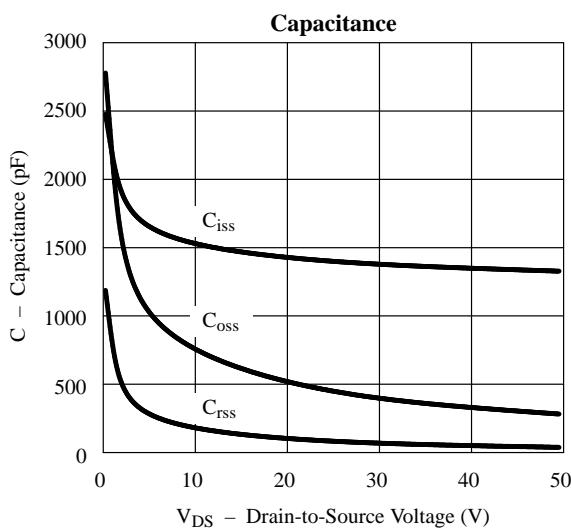
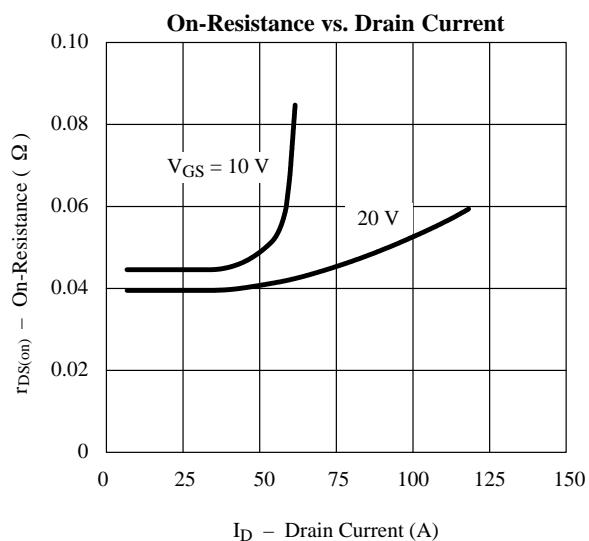
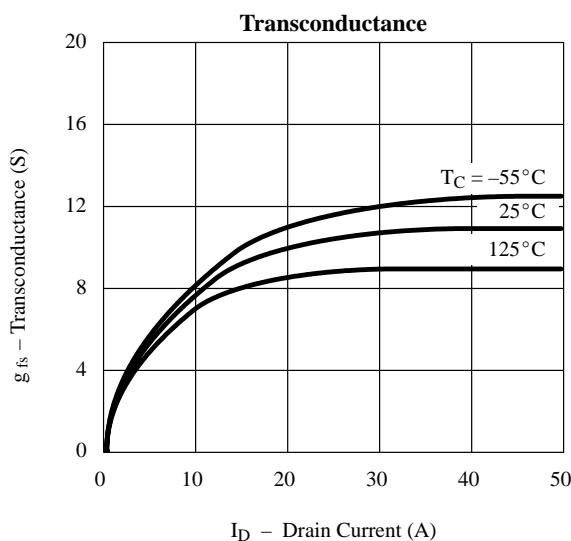
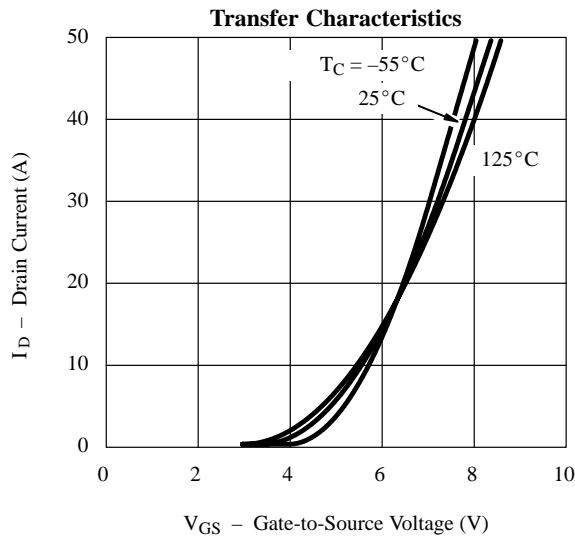
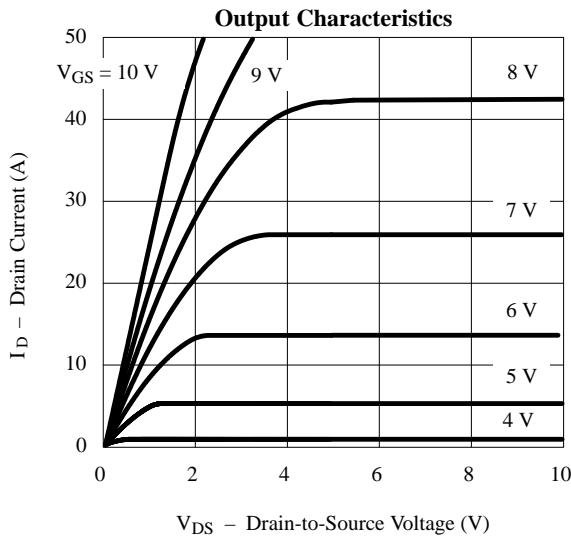
Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

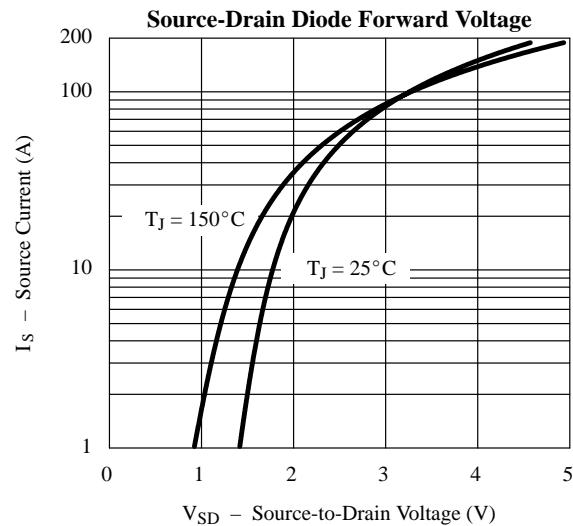
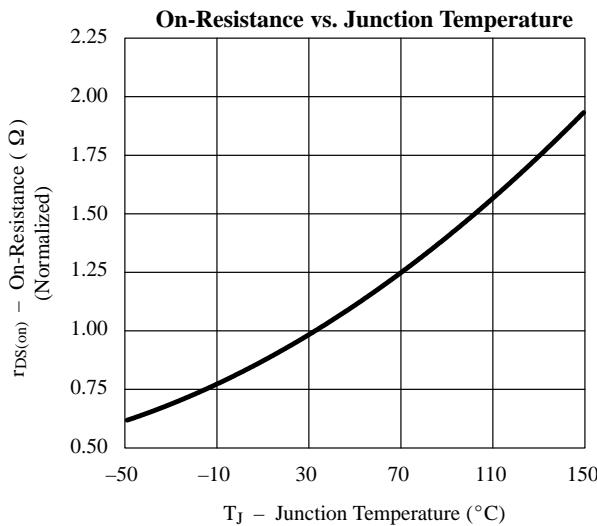
Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ ^a	Max	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250 \mu\text{A}$	2.0		4.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 80 \text{ V}, V_{\text{GS}} = 0 \text{ V}$			25	μA
		$V_{\text{DS}} = 80 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 125^\circ\text{C}$			250	
On-State Drain Current ^b	$I_{\text{D}(\text{on})}$	$V_{\text{DS}} = 10 \text{ V}, V_{\text{GS}} = 10 \text{ V}$	20			A
Drain-Source On-State Resistance ^b	$r_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10 \text{ V}, I_D = 12 \text{ A}$		0.06	0.075	Ω
		$V_{\text{GS}} = 10 \text{ V}, I_D = 12 \text{ A}, T_J = 125^\circ\text{C}$		0.11	0.14	
Forward Transconductance ^b	g_{fs}	$V_{\text{DS}} = 15 \text{ V}, I_D = 12 \text{ A}$	5.0	8.0		S
Dynamic						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0 \text{ V}, V_{\text{DS}} = 25 \text{ V}, f = 1 \text{ MHz}$		1400		pF
Output Capacitance	C_{oss}			480		
Reverse Transfer Capacitance	C_{rss}			110		
Total Gate Charge ^c	Q_g	$V_{\text{DS}} = 50 \text{ V}, V_{\text{GS}} = 10 \text{ V}, I_D = 20 \text{ A}$		35	50	nC
Gate-Source Charge ^c	Q_{gs}			10	20	
Gate-Drain Charge ^c	Q_{gd}			18	25	
Turn-On Delay Time ^c	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 50 \text{ V}, R_L = 2.5 \Omega$ $I_D \cong 20 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, R_G = 4.7 \Omega$		13	30	ns
Rise Time ^c	t_r			85	120	
Turn-Off Delay Time ^c	$t_{\text{d}(\text{off})}$			35	80	
Fall Time ^c	t_f			75	95	
Source-Drain Diode Ratings and Characteristics						
Continuous Current	I_S				20	A
Pulsed Current	I_{SM}				80	
Diode Forward Voltage ^b	V_{SD}	$I_F = 20 \text{ A}, V_{\text{GS}} = 0 \text{ V}$			2.5	V
Reverse Recovery Time	t_{rr}	$I_F = 20 \text{ A}, \text{di}/\text{dt} = 100 \text{ A}/\mu\text{s}$		150	400	ns
Reverse Recovery Charge	Q_{rr}			0.5		μC

Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- c. Independent of operating temperature.

Typical Characteristics (25°C Unless Otherwise Noted)



Typical Characteristics (25°C Unless Otherwise Noted)

Thermal Ratings
